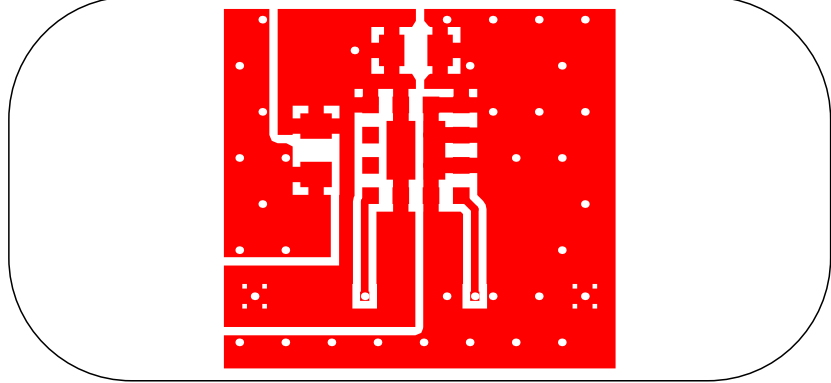
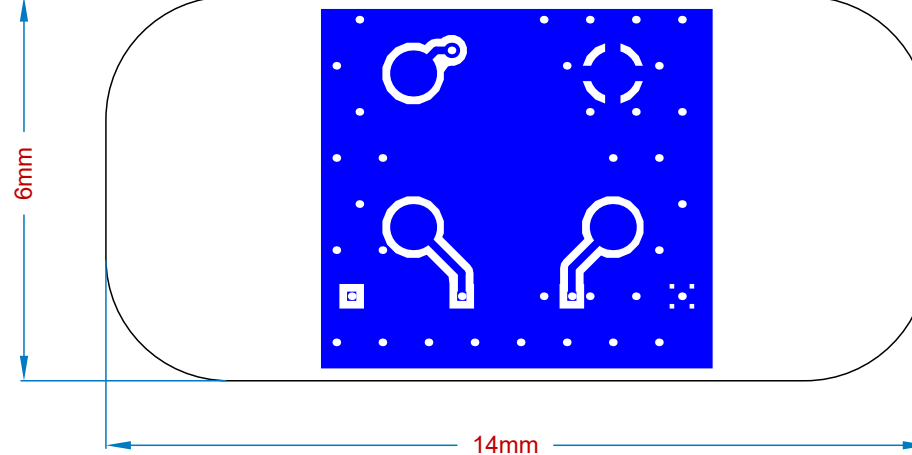


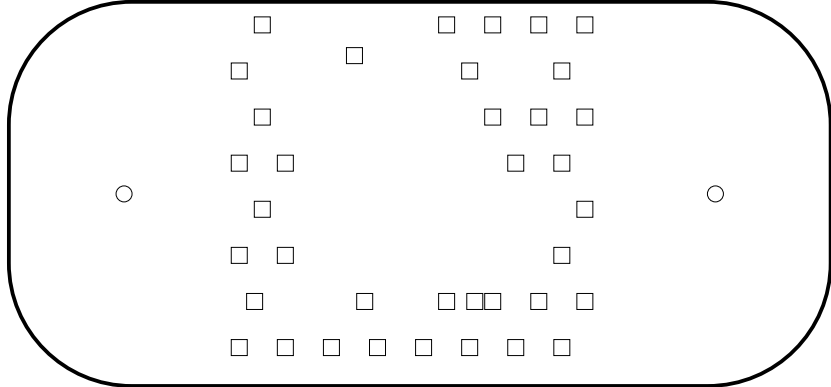
Top Layer (Scale 8:1)



Bottom Layer (Scale 8:1)



Drill Drawing View (Scale 8:1)



Drill Table

Symbol	Count	Hole Size	Plated
□	37	5mil	Plated
○	2	98mil	Non-Plated
39 Total			

Notes

- Board material is Polyimide.
- Manufacture to IPC-6012A Class 2 quality level.
- Minimum trace width/spacing is 3mil.
- Surface finish must be ENIG (Electroless Nickel Immersion Gold).
 - Electroless nickel thickness: 3 - 6um (refer to IPC-4552).
 - Immersion gold thickness: 0.05um minimum.
- Silkscreen (overlay) is white on both sides.
- Soldermask is green.
- All vias should be tented.

Layer Stack

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	1mil	SM-001	Solder Mask	GTS
Lead-Free	Top Surface Finish	1mil		Surface Finish	
CF-004	Top Layer	1mil		Signal	GTL
Core		2mil	Core-001	Dielectric	
CF-004	Bottom Layer	1mil		Signal	GBL
Lead-Free	Bottom Surface Finish	1mil		Surface Finish	
Surface Material	Bottom Solder	1mil	SM-001	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 8mil					

FOCUS		Project: XLBoard	
Schematic: XLBOARD DRAFTMAN			Version: 1.0
Design by: José Bentancour			Date: 11/07/2023
Reviewed by: Alvaro Rios			Date: 12/01/2023
Comments:			